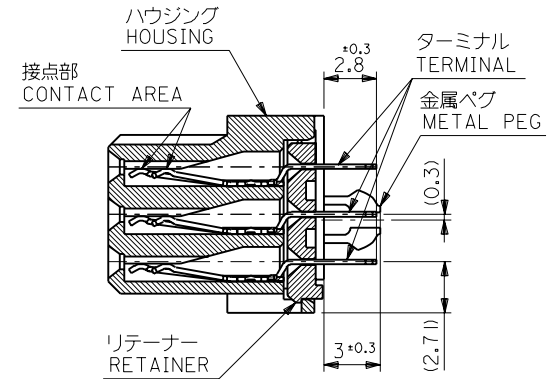
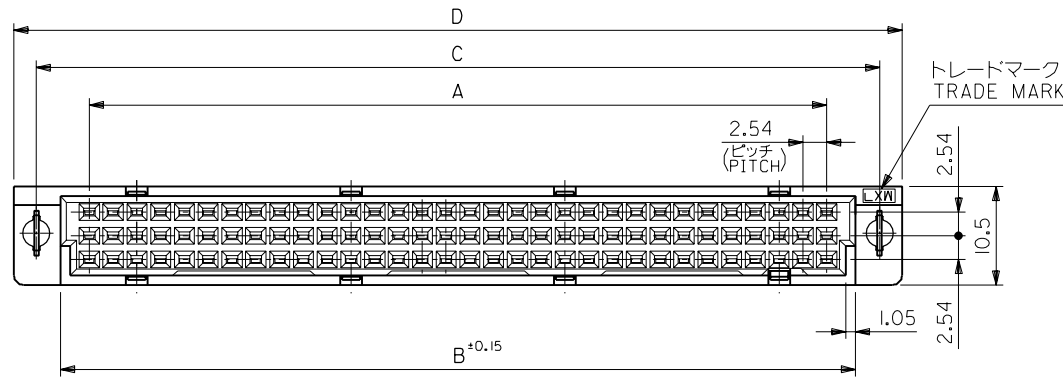
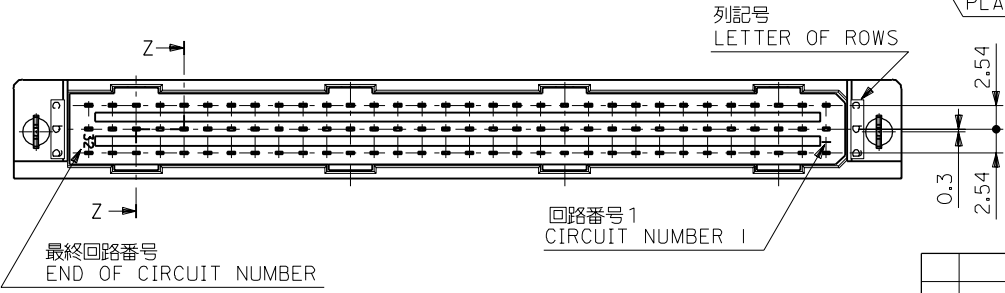
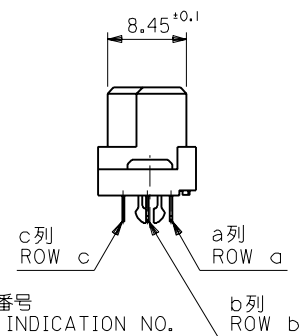
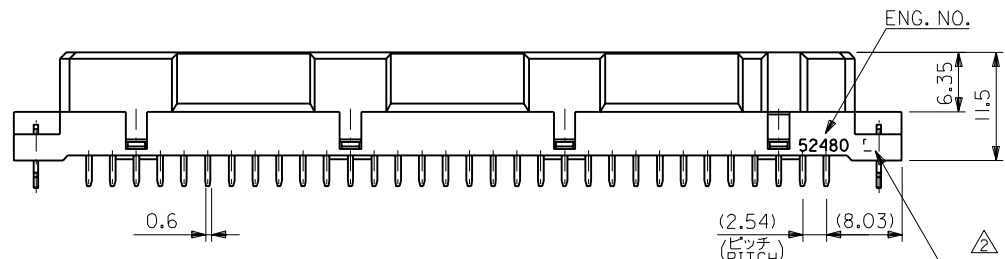


DWG. NO. SD-52480-*****



断面 Z-Z
SECT. Z-Z
(SCALE: 4-1)



94.8	90	84.9	78.74	52480-096*	96
54.16	49.36	44.26	38.1	52480-048*	48
D	C	B	A	ENG. NO.	種数 CIRCUIT

角度 ANGLE	公差 TOLERANCES	記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE
30以上 OVER	+0.3	B	変更 REVISD (J20670)	M.F. H.H.	'92/7/30
10以上 30未満 UNDER	+0.25	A	変更 REVISD (J10138)	T.I. H.H.	'92/2/20
10未満 UNDER	+0.2	O	新規作成 RELEASED (J00922)	T.I. H.H.	'90/8/27

材料 MATERIAL	注記参照 SEE NOTES
仕上げ FINISH	注記参照 SEE NOTES
適用電線範囲 WIRE RANGE	---
被覆外径 INS. RANGE	---
DRAWN BY '90/8/27 I.I.TO	CHK'D BY '92/7/30 H.HIRAMOTO
APP'D BY '92/7/30 M.FUKUSHIMA	尺度 SCALE 2 - 1

MOLLEX MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
REVISE ONLY ON CAD SYSTEM	
TITLE 名称	
2.54 BOARD TO BOARD CONN. HS'G ASS'Y WITH METAL PEG (TRIPLE ROW)	
DWG. NO.	SHEET 1 OF 2 REV
SD-52480-*****	B

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

:MM

52480G.S02

注記
NOTES

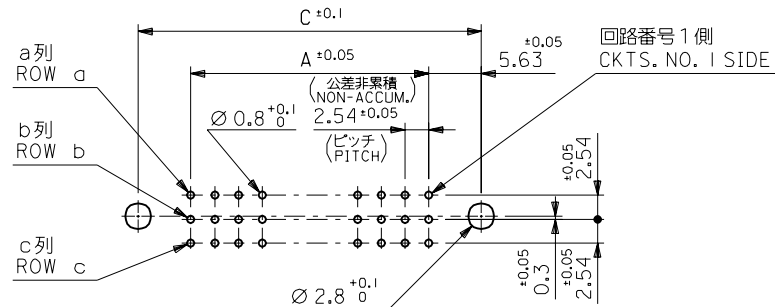
1. 材質
MATERIAL

ハウジング : ガラス入り PBTP (白色), UL94V-0
HOUSING : GLASS FILLED PBTP (WHITE), UL94V-0
リテーナー : ガラス入り PBTP (白色), UL94V-0
RETAINER : GLASS FILLED PBTP (WHITE), UL94V-0
ターミナル : リン青銅 (t=0.25)
TERMINAL : PHOSPHOR BRONZE (t=0.25)
金属ペグ : リン青銅、銅下地半田メッキ (t=0.48)
METAL PEG : PHOSPHOR BRONZE (t=0.48), TIN-LEAD OVER COPPER PLATING

メッキ仕様及び仕様番号
PLATING AND PLATING INDICATION NUMBER

52480-***3	0.76	1.0	1.0	3
52480-***2	0.5			2
52480-***1	0.3			1
52480-***0	0.1			0
ENG. NO.	接点部 金メッキ [μm以上] CONTACT AREA GOLD PLATING [μmMIN.]	半田付け部 半田メッキ [μm以上] SOLDER AREA TIN-LEAD PLATING [μmMIN.]	下地 ニッケルメッキ [μm以上] UNDER PLATE NICKEL PLATING [μmMIN.]	メッキ仕様番号 PLATING INDICATION NO.

3. 嵌合相手 : 53233, 53234, 53296, 53317, 53318, 53320 シリーズ
MATES WITH : 53233, 53234, 53296, 53317, 53318, 53320 SERIES



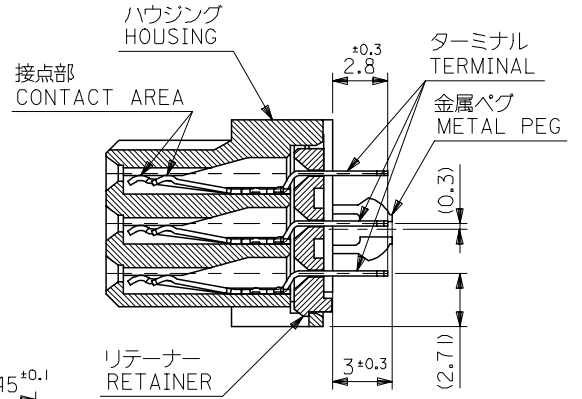
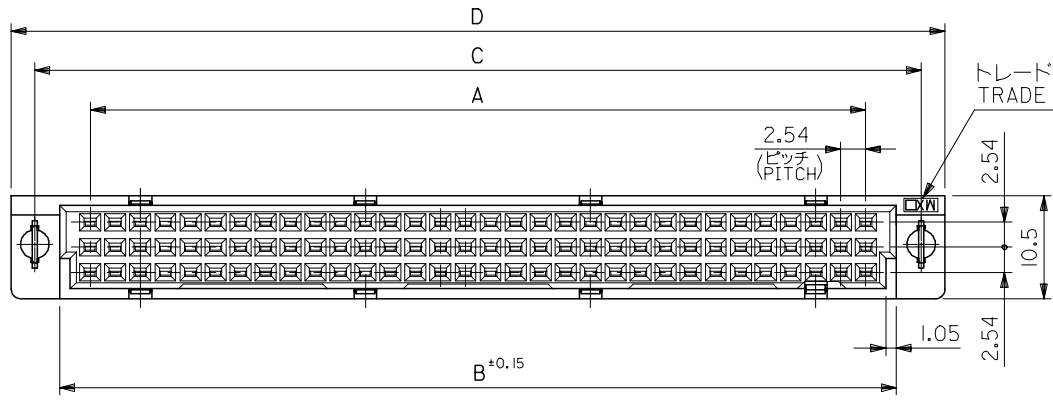
基板穴推奨寸法
RECOMMENDED P. C. BOARD LAYOUT
(部品実装側) (VIEW ON COMPONENT SIDE) (t=1.6)

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

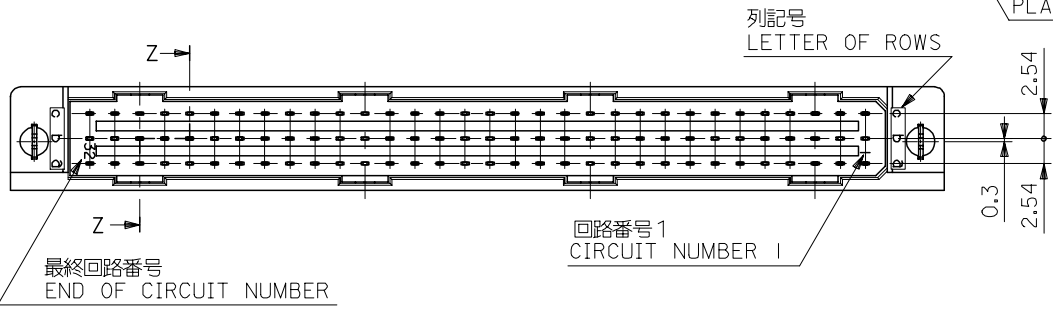
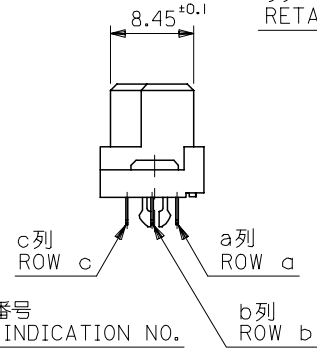
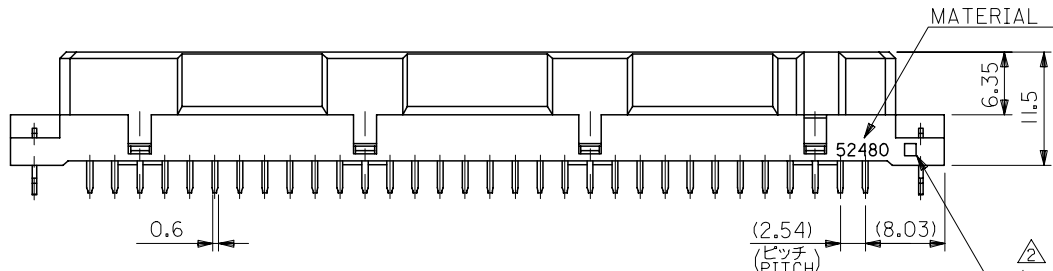
				材料 MATERIAL		注記参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
				仕上げ FINISH		注記参照 SEE NOTES		REVISE ONLY ON CAD SYSTEM	
				適用電線範囲 WIRE RANGE		—H—		TITLE 名称	
				被覆外径 INS. RANGE		—H—		2.54 BOARD TO BOARD CONN. HS'G ASS'Y WITH METAL PEG (TRIPLE ROW)	
				DRAWN BY '90/8/27 T.ITO		CHK'D BY '92/7/30 H.HIRAMOTO		DWG. NO. SHEET 2 OF 2 REV	
				APP'D BY '92/7/30 M.FUKUSHIMA		尺度 SCALE 2 - 1		SD-52480-***** B	
角度 ANGLE		±3°		記号 LTR		変更内容 REVISION RECORD		DR. / CHK. 日付 DATE	
30°以上 OVER		+0.3	B	変更 REVISED (J20670)	M.F. H.H.	'92/7/30			
10°以上 30°未満 OVER UNDER		+0.25	A	変更 REVISED (J10138)	T.I. H.H.	'91/2/20			
10°未満 UNDER		+0.2	O	新規作成 RELEASED (J00922)	T.I. H.H.	'90/8/27			
一般公差 GENERAL TOLERANCES									

10 9 8 7 6 5 4 3 2 1

F
E
D
C
B
A



断面 Z-Z
SECT. Z-Z
(SCALE: 4-1)



94.8	90	84.9	78.74	52480-96I*	96
54.16	49.36	44.26	38.1	52480-48I*	48
D	C	B	A	MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2006-2007 DRW:MKOND002 CHK:DAIKITA APP:NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		TITLE 2.54 B/B CONN. HS'G ASS'Y (TRIPLE ROW) -LEAD FREE- MOLEX INCORPORATED	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		10 UNDER	±0.2	DRAWN BY Y.SAKIYAMA	DATE 2004/05/10				
		10 OVER 30 UNDER	±0.25	CHECKED BY M.SASAO	DATE 2004/05/10				
		30 OVER	±0.3	APPROVED BY M.SASAO	DATE 2004/05/10				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-52480-002		SHEET NO. 1 OF 2	
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

注記
NOTES

1. 材質
MATERIAL

ハウジング : ガラス入りポリエステル(白色) , UL94V-0
HOUSING : GLASS FILLED POLYESTER, (WHITE), UL94V-0
リテーナー : ガラス入りポリエステル(白色) , UL94V-0
RETAINER : GLASS FILLED POLYESTER, (WHITE), UL94V-0
ターミナル : リン青銅 (t=0.25)
TERMINAL : PHOSPHOR BRONZE (t=0.25)
金属ペグ : リン青銅、ニッケル下地 錫メッキ (t=0.48)
METAL PEG : PHOSPHOR BRONZE (t=0.48), TIN OVER NICKEL PLATING

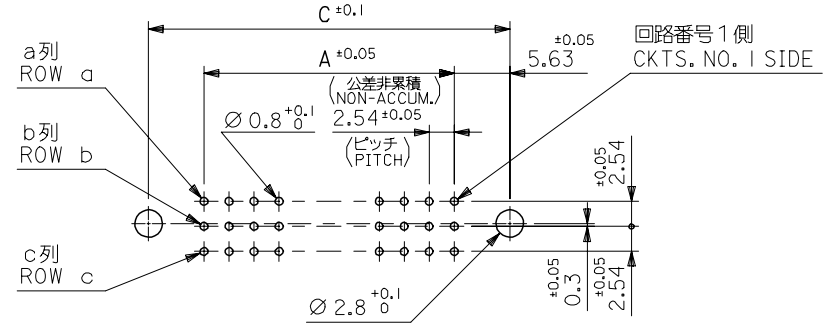
※52480-**14 については、ハウジング及びリテーナーにおいて
フラックス付着防止液 (JES-43) を塗布したもの。
52480-**14 : TREATED WITH FLUX ANTI-WICKING AGENT.
(HOUSING AND RETAINER TO BE SPREAD JES-43)

メッキ仕様及び仕様番号
PLATING AND PLATING INDICATION NUMBER

52480-**14	0.1	1.0	2.0	4
52480-**13	0.76			3
52480-**12	0.5			2
52480-**11	0.3			1
52480-**10	0.1			0
MATERIAL. NO.	接点部 金メッキ [μm以上] CONTACT AREA GOLD PLATING [μmMIN.]	半田付け部 錫メッキ [μm以上] SOLDER AREA TIN PLATING [μmMIN.]	下地メッキ ニッケルメッキ [μm以上] UNDER PLATE NICKEL PLATING [μmMIN.]	メッキ 仕様番号 PLATING INDICATION NUMBER

3. 嵌合相手: 53233, 53234, 53296, 53317, 53318, 53320 シリーズ
MATES WITH : 53233, 53234, 53296, 53317, 53318, 53320 SERIES

4. 本製品は52480-**** の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52480-****.



基板穴推奨寸法
RECOMMENDED P.C. BOARD LAYOUT
(部品実装側) (t=1.6)
(VIEW ON COMPONENT SIDE)

REVISED EC NO: J2006-2007 DRW:MKOND002 2005/12/15 CHKD:NUKITA 2005/12/19 APPR:NUKITA 2005/12/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		52480-**14		MODEL NO.	
	10 UNDER ±0.2		DRAWN BY DATE Y.SAKIYAMA 2004/05/10		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 OVER 30 UNDER ±0.25		CHECKED BY DATE M.SASAO 2004/05/10		TITLE 2.54 B/B CONN. HS'G ASS'Y (TRIPLE ROW) -LEAD FREE-			
	30 OVER ±0.3		APPROVED BY DATE M.SASAO 2004/05/10					
	ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET No.1		SD-52480-002		2 OF 2		

SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION